

Features

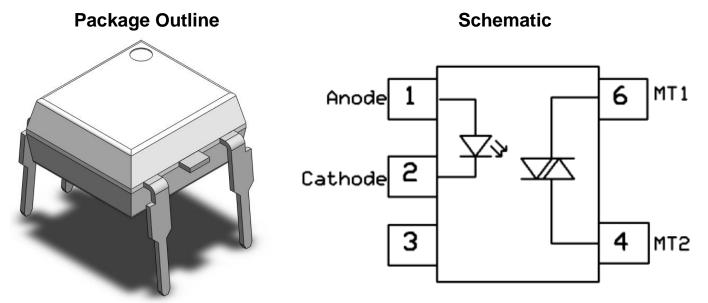
- High isolation 5000 VRMS
- Patented coplanar structure DMC-Isolator®
- Peak Breakdown Voltage
 - 250V CT3010-5L, CT3011-5L, CT3012-5L
 - 400V CT3020-5L, CT3021-5L, CT3022-5L,
 CT3023-5L
- Operating Temperature range 55 °C to 100 °C
- External Creepage ≥ 7.4mm
- Distance Through Isolation ≥ 0.4mm
- Clearance Distance ≥ 7.5mm (S/SL Type)
- Clearance Distance ≥ 8.0mm (M Type)
- RoHS and REACH Compliance
- Halogen Free Compliance (Optional)
- MSL class 1
- Regulatory Approvals
 - ✓ UL UL1577 (E364000)
 - ✓ VDE EN60747-5-5 (40039590)
 - ✓ CQC GB4943.1, GB8898 (14001105802)
 - ✓ IEC62368 (FI/41119)

Description

The CT3010-5L, CT3011-5L, CT3012-5L, CT3020-5L, CT3021-5L, CT3022-5L and CT3023-5L consists of a Random Phase Photo Triac optically coupled to an Infrared-emitting diode in a 5-lead DIP package DMC-Isolator® with different lead forming options.

Applications

- Motor Controls
- Lamp ballasts
- Static AC Power Switch
- Solenoid/ Valve Control



Note: Different lead forming options available. See package dimension.



Absolute Maximum Ratings $T_A = 25^{\circ}C$, unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters		Ratings	Units	Notes		
Viso	Isolation voltage (AC, 1 min	ute, 40 ~ 60% R.H.)	5000	V _{RMS}			
Topr	Operating temperature		-55 ~ +100	°C			
Тѕтс	Storage temperature		-55 ~ +150	°C			
Tsol	Soldering temperature (For	10 seconds)	260	°C			
TJ	Junction temperature		115	°C			
Emitter	Emitter						
l _F	Forward current	60	mA				
I _{F(TRANS)}	Peak transient current (≤1µs P.W,300pps)		1	А			
V _R	Reverse voltage		6	V			
P _D	Power dissipation		100	mW			
Detector							
P _D	Power dissipation		300	mW			
	Off-State Output Terminal	CT3010-5L,3012-5L,3022-5L	250	V			
V_{DRM}	Voltage	CT3020-5L,3021-5L,3022-5L,3023-5L	400	V			
I _{TM}	RMS on-state current		100	mA			
I _{TSM}	Peak Repetitive Surge Current		1	А			

Electrical Characteristics $T_A = 25^{\circ}$ C, unless otherwise specified

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I _F =10mA	-	1.24	1.5	V	
I _R	Reverse Current	V _R = 6V	-	-	5	μΑ	
Cin	Input Capacitance	f= 1MHz	-	45	-	pF	

Detector Characteristics

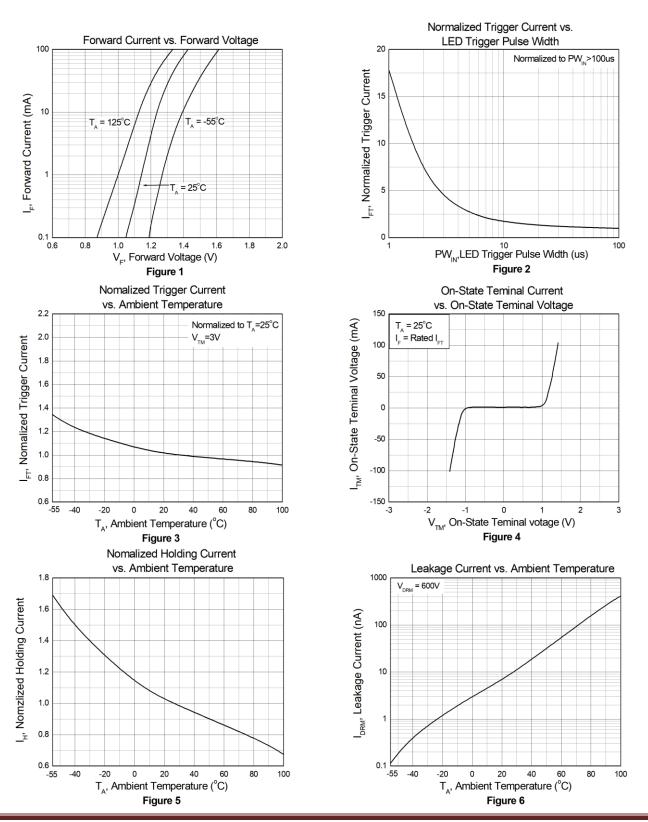
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
I _{DRM}	Peak Blocking Current	I _F = 0mA, V _{DRM} = Rated V _{DRM}	ı	ı	100	nA	
Vтм	Peak On-State Voltage	I _F = Rated I _{FT} , I _{TM} = 100mA		-	2.5	V	
dv/dt	Critical Rate of Rise off-State Voltage	V _{PEAK} = Rated V _{DRM}	-	100	-	V/μs	

Transfer Characteristics

Symbol	Parar	neters	Test Conditions	Min	Тур	Мах	Units	Notes
		CT3020-5L	Terminal Voltage = 3V	-	•	30	mA	
	Innut Trigger	CT3010-5L,		-	-	15		
IFT	Input Trigger IFT Current	CT3021-5L						
		CT3011-5L,	- I _{TM} =100mA		-	10		
		CT3022-5L	:T3022-5L					
			Terminal Voltage from "ON" to					
I _H	Holding Current		"OFF"	-	250	-	μΑ	
			"ON" state I _F =0mA					
R _{IO}	Isolation Resistance		V _{IO} = 500V _{DC} , 40 ~ 60% R.H.	1x10 ¹¹	-	-	Ω	
Сю	Isolation Capacitance		f= 1MHz	-	0.25	-	pF	

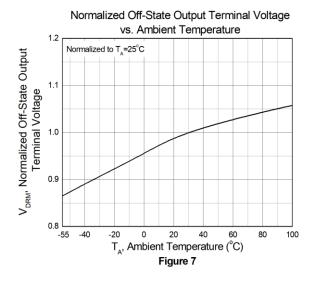


Typical Characteristic Curves $T_A = 25$ °C, unless otherwise specified



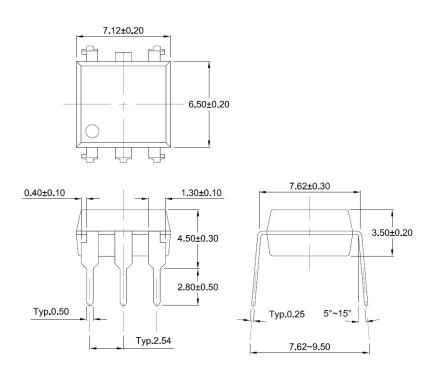


Typical Characteristic Curves $\tau_A = 25$ °C, unless otherwise specified (Continued)

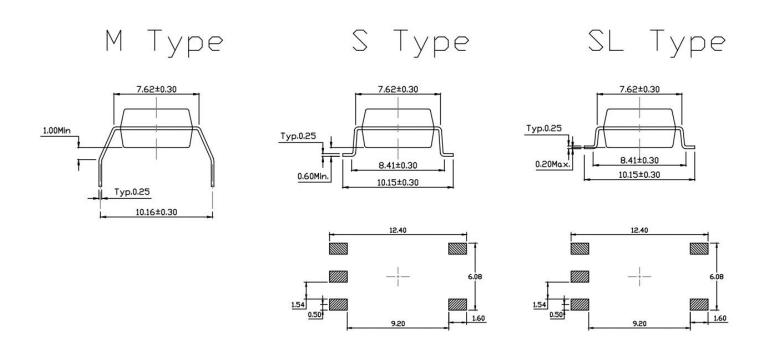




Package Dimension Dimensions in mm unless otherwise stated

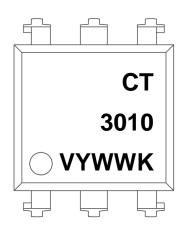


Forming Option Dimensions in mm unless otherwise stated





Marking Information



Note:

CT : Denotes "CT Micro"

3010 : Part Number

V : VDE Safety Mark Option (Blank or V)

Y : One Digit Year CodeWW : Two Digit Work WeekK : Manufacturing Code

Ordering Information

CT301X(V)(Y)(Z)-5L-G, CT302X(V)(Y)(Z)-5L-G

CT = Denotes "CT Micro"

301X = Part Numbers (Current Ration Option X=0, 1 or 2)

302X = Part Numbers (Current Ration Option X=0, 1, 2 or 3)

V = VDE Safety Mark Option (Blank or V)

Y = Lead Form Option (S, SL, M or Blank)

Z = Tape and Reel Option (Blank, T1, T2, T3 or T4)

5L = 5 PIN Lead Frame

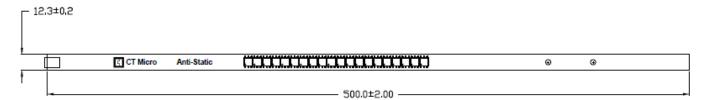
G = Material Option (G: Halogen Free, Blank: Non-Halogen Free)

Option	Description	Quantity
None	Standard 6 Pin Dip	50Units/Tube
M	Gullwing (400mil) Lead Forming	50Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming – With Option 1 Taping	1000 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming – With Option 2 Taping	1000 Units/Reel

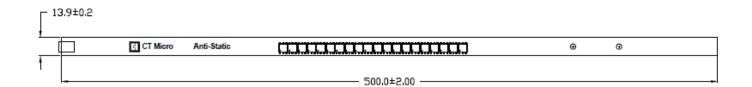


Carrier Specifications Dimensions in mm unless otherwise stated

Tube Option Standard DIP

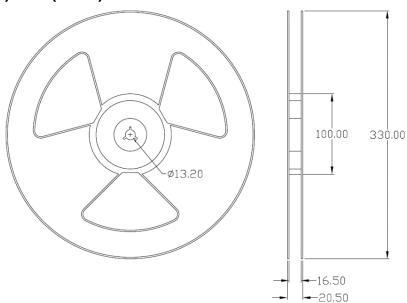


Tube Option M Type



Reel Dimension All dimensions are in mm, unless otherwise stated

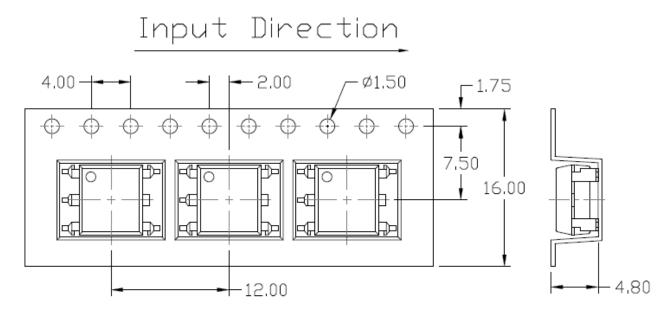
Option S(T1/T2) & SL(T1/T2)



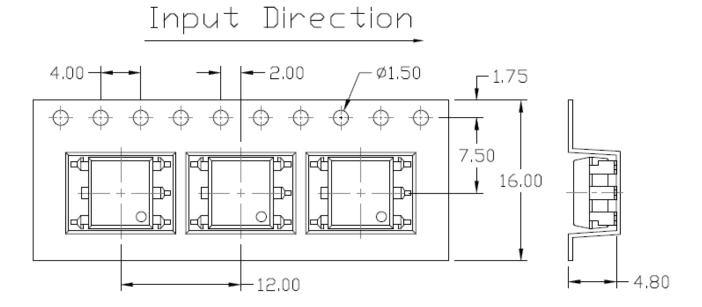


Carrier Tape Specifications Dimensions in mm unless otherwise stated

Option S (T1) & SL (T1)



Option S (T2) & SL (T2)



Solderability spec (follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

Wave soldering (follow the JEDEC standard JESD22-A111)

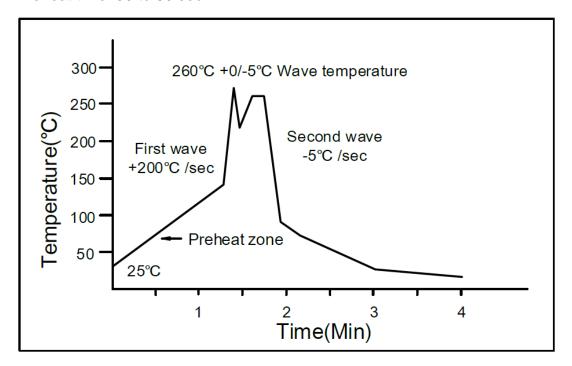
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature: 25 to 140°C.

Preheat time: 30 to 80 sec.



Iron Soldering (follow the standard MIL-STD 202G, Method 210F)

Allow single lead soldering in every single process.

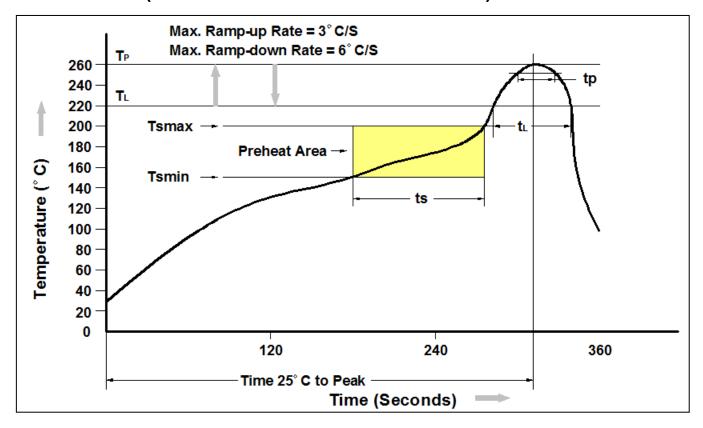
One time soldering is recommended.

Temperature: 350±10°C

Time: 5 sec max.



Reflow Profile (follow the JEDEC standard J-STD-020)



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t _P)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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